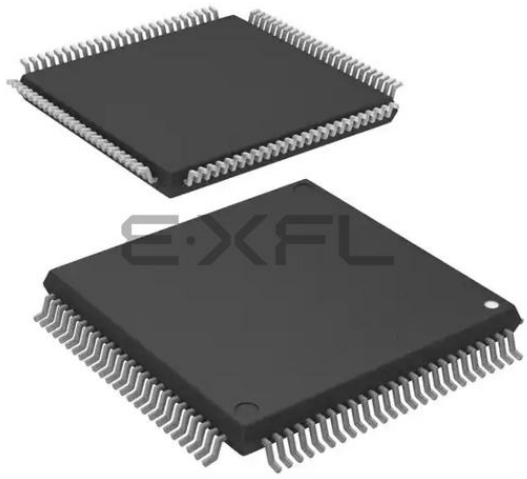

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	M16C/60
Core Size	16-Bit
Speed	32MHz
Connectivity	EBI/EMI, I²C, SIO, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	85
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 26x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LFQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f36506dfb-30

Table 1.2 Specifications for the 128-Pin Package (2/2)

Item	Function	Description
Timers	Timer A	16-bit timer × 5 Timer mode, event counter mode, one-shot timer mode, pulse width modulation (PWM) mode Event counter two-phase pulse signal processing (two-phase encoder input) × 3 Programmable output mode × 3
	Timer B	16-bit timer × 6 Timer mode, event counter mode, pulse period measurement mode, pulse width measurement mode
	Three-phase motor control timer functions	• Three-phase inverter control (timer A1, timer A2, timer A4, timer B2) • On-chip dead time timer
	Real-time clock	Count: seconds, minutes, hours, days of the week
	PWM function	8 bits × 2
	Remote control signal receiver	• 2 circuits • 4 wave pattern matchings (differentiate wave pattern for headers, data 0, data 1, and special data) • 6-byte receive buffer (1 circuit only) • Operating frequency of 32 kHz
Serial Interface	UART0 to UART2, UART5 to UART7	Clock synchronous/asynchronous × 6 channels I^2C-bus, IEBus, special mode 2 SIM (UART2)
	SI/O3, SI/O4	Clock synchronization only × 2 channels
Multi-master I^2C-bus Interface		1 channel
CEC Functions (2)		CEC transmit/receive, arbitration lost detection, ACK automatic output, operation frequency of 32 kHz
A/D Converter		10-bit resolution × 26 channels, including sample and hold function Conversion time: 1.72 µs
D/A Converter		8-bit resolution × 2 circuits
CRC Calculator		CRC-CCITT ($X^{16} + X^{12} + X^5 + 1$), CRC-16 ($X^{16} + X^{15} + X^2 + 1$) compliant
Flash Memory		• Program and erase power supply voltage: 2.7 to 5.5 V • Program and erase cycles: 1,000 times (program ROM 1, program ROM 2), 10,000 times (data flash) • Program security: ROM code protect, ID code check
Debug Functions		On-chip debug, on-board flash rewrite, address match interrupt × 4
Operation Frequency/Supply Voltage		32 MHz/VCC1 = 2.7 to 5.5 V, VCC2 = 2.7 V to VCC1
Current Consumption		Described in Electrical Characteristics
Operating Temperature		-20°C to 85°C, -40°C to 85°C (1)
Package		128-pin LQFP: PLQP0128KB-A (Previous package code: 128P6Q-A)

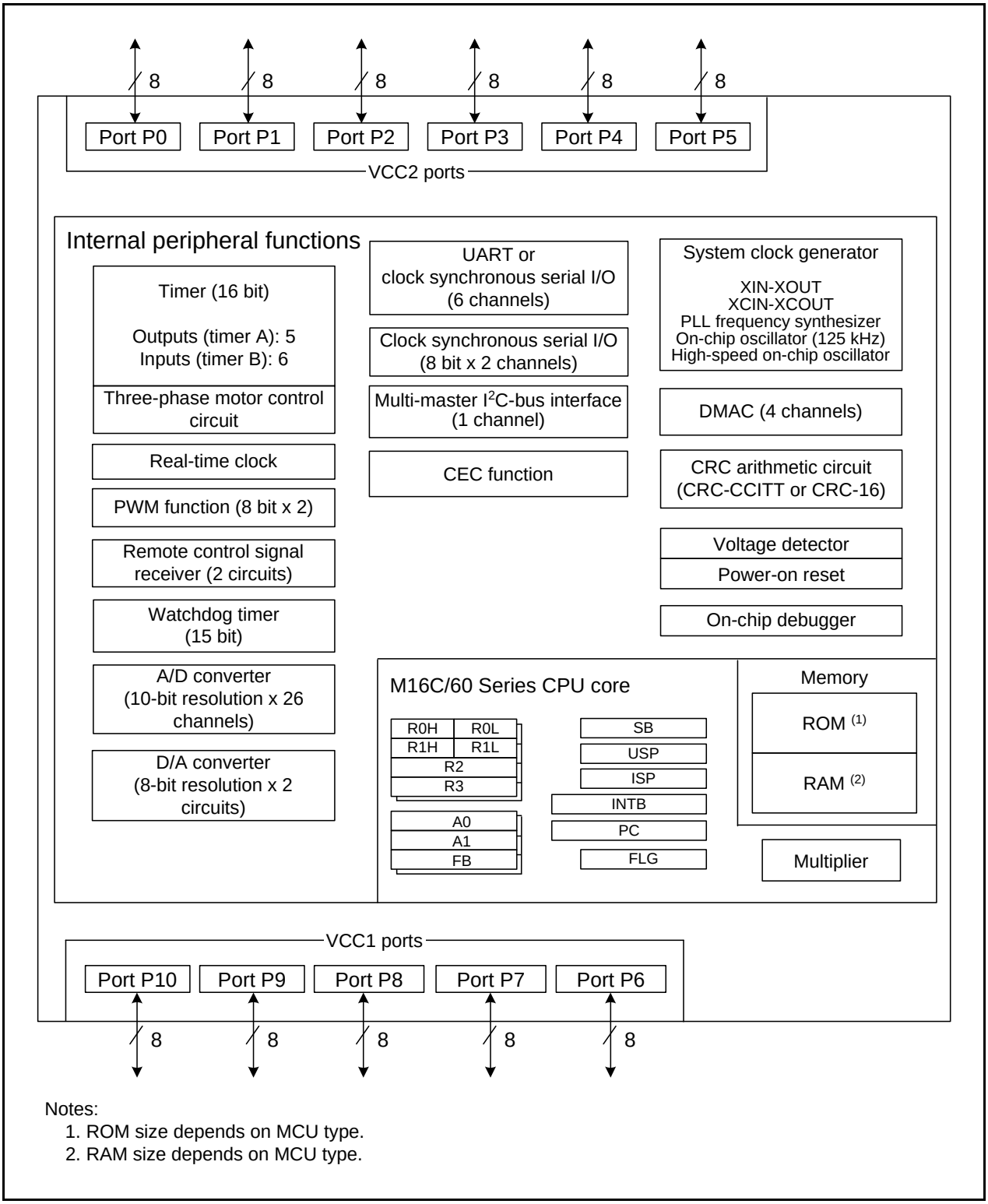
Notes:
1. See Table 1.5 “Product List (1/2)” and Table 1.6 “Product List (2/2)” for the operating temperature.
2. The CEC function indicates circuitry which supports the transmission and reception of CEC signals standardized by the High-Definition Multimedia Interface (HDMI). HDMI and High-Definition Multimedia Interface are registered trademarks of HDMI Licensing, LLC.

Table 1.6 Product List (2/2) As of July 2012

Part No.	ROM Capacity			RAM Capacity	Package Code	Remarks
	Program ROM 1	Program ROM 2	Data flash			
R5F3651TNFC	768 KB	16 KB	4 KB × 2 blocks	47 KB	PLQP0128KB-A	Operating temperature -20°C to 85°C
R5F3650TNFA					PRQP0100JD-B	
R5F3650TNFB					PLQP0100KB-A	
R5F3651TDFC					PLQP0128KB-A	Operating temperature -40°C to 85°C
R5F3650TDFA					PRQP0100JD-B	
R5F3650TDFB					PLQP0100KB-A	

(D): Under development
(P): Planning

Previous package codes are as follows:
PLQP0128KB-A: 128P6Q-A
PRQP0100JD-B: 100P6F-A
PLQP0100KB-A: 100P6Q-A



Notes:
1. ROM size depends on MCU type.
2. RAM size depends on MCU type.

Figure 1.4 Block Diagram for the 100-Pin Package

Table 1.7 Pin Names for the 128-Pin Package (1/3)

Pin No.	Control Pin	Port	I/O Pin for Peripheral Function				Bus Control Pin
			Interrupt	Timer	Serial interface	A/D converter, D/A converter	
1	VREF						
2	AVCC						
3		P9_7			SIN4	$\overline{ADTRG}$	
4		P9_6			SOUT4	ANEX1	
5		P9_5			CLK4	ANEX0	
6		P9_4		TB4IN/PWM1		DA1	
7		P9_3		TB3IN/PWM0		DA0	
8		P9_2		TB2IN/PMC0	SOUT3		
9		P9_1		TB1IN/PMC1	SIN3		
10		P9_0		TB0IN	CLK3		
11		P14_1					
12		P14_0					
13	BYTE						
14	CNVSS						
15	XCIN	P8_7					
16	XCOUT	P8_6					
17	$\overline{RESET}$						
18	XOUT						
19	VSS						
20	XIN						
21	VCC1						
22		P8_5	$\overline{NMI}$	$\overline{SD}$	CEC		
23		P8_4	$\overline{INT2}$	ZP			
24		P8_3	$\overline{INT1}$				
25		P8_2	$\overline{INT0}$				
26		P8_1		TA4IN/$\overline{U}$	$\overline{CTS5}$/$\overline{RTS5}$		
27		P8_0		TA4OUT/U	RXD5/SCL5		
28		P7_7		TA3IN	CLK5		
29		P7_6		TA3OUT	TXD5/SDA5		
30		P7_5		TA2IN/$\overline{W}$			
31		P7_4		TA2OUT/W			
32		P7_3		TA1IN/$\overline{V}$	$\overline{CTS2}$/$\overline{RTS2}$		
33		P7_2		TA1OUT/V	CLK2		
34		P7_1		TA0IN/TB5IN	RXD2/SCL2/SCLMM		
35		P7_0		TA0OUT	TXD2/SDA2/SDAMM		
36		P6_7			TXD1/SDA1		
37	VCC1						
38		P6_6			RXD1/SCL1		
39	VSS						
40		P6_5			CLK1		
41		P6_4			$\overline{CTS1}$/$\overline{RTS1}$/$\overline{CTS0}$/CLKS1		
42		P6_3			TXD0/SDA0		
43		P6_2			RXD0/SCL0		
44		P6_1			CLK0		
45		P6_0		RTCOUT	$\overline{CTS0}$/$\overline{RTS0}$		
46		P13_7					
47		P13_6					
48		P13_5					
49		P13_4					
50	CLKOUT	P5_7					$\overline{RDY}$

Table 1.10 Pin Names for the 100-Pin Package (1/2)

Pin No.		Control Pin	Port	I/O Pin for Peripheral Function				Bus Control Pin
FA	FB			Interrupt	Timer	Serial interface	A/D converter, D/A converter	
1	99		P9_6			SOUT4	ANEX1	
2	100		P9_5			CLK4	ANEX0	
3	1		P9_4		TB4IN/PWM1		DA1	
4	2		P9_3		TB3IN/PWM0		DA0	
5	3		P9_2		TB2IN/PMC0	SOUT3		
6	4		P9_1		TB1IN/PMC1	SIN3		
7	5		P9_0		TB0IN	CLK3		
8	6	BYTE						
9	7	CNVSS						
10	8	XCIN	P8_7					
11	9	XCOUT	P8_6					
12	10	$\overline{\text{RESET}}$						
13	11	XOUT						
14	12	VSS						
15	13	XIN						
16	14	VCC1						
17	15		P8_5	$\overline{\text{NMI}}$	$\overline{\text{SD}}$	CEC		
18	16		P8_4	$\overline{\text{INT2}}$	ZP			
19	17		P8_3	$\overline{\text{INT1}}$				
20	18		P8_2	$\overline{\text{INT0}}$				
21	19		P8_1		TA4IN/$\overline{\text{U}}$	$\overline{\text{CTS5/RTS5}}$		
22	20		P8_0		TA4OUT/U	RXD5/SCL5		
23	21		P7_7		TA3IN	CLK5		
24	22		P7_6		TA3OUT	TXD5/SDA5		
25	23		P7_5		TA2IN/$\overline{\text{W}}$			
26	24		P7_4		TA2OUT/W			
27	25		P7_3		TA1IN/$\overline{\text{V}}$	$\overline{\text{CTS2/RTS2}}$		
28	26		P7_2		TA1OUT/V	CLK2		
29	27		P7_1		TA0IN/TB5IN	RXD2/SCL2/SCLMM		
30	28		P7_0		TA0OUT	TXD2/SDA2/SDAMM		
31	29		P6_7			TXD1/SDA1		
32	30		P6_6			RXD1/SCL1		
33	31		P6_5			CLK1		
34	32		P6_4			$\overline{\text{CTS1}}$/RTS1/$\overline{\text{CTS0}}$/ CLKS1		
35	33		P6_3			TXD0/SDA0		
36	34		P6_2			RXD0/SCL0		
37	35		P6_1			CLK0		
38	36		P6_0		RTCOUT	$\overline{\text{CTS0/RTS0}}$		
39	37	CLKOUT	P5_7					$\overline{\text{RDY}}$
40	38		P5_6					ALE
41	39		P5_5					$\overline{\text{HOLD}}$
42	40		P5_4					$\overline{\text{HLDA}}$
43	41		P5_3					BCLK
44	42		P5_2					$\overline{\text{RD}}$
45	43		P5_1					$\overline{\text{WRH/BHE}}$
46	44		P5_0					$\overline{\text{WRL/WR}}$
47	45		P4_7		PWM1	TXD7/SDA7		$\overline{\text{CS3}}$
48	46		P4_6		PWM0	RXD7/SCL7		$\overline{\text{CS2}}$
49	47		P4_5			CLK7		$\overline{\text{CS1}}$
50	48		P4_4			$\overline{\text{CTS7/RTS7}}$		$\overline{\text{CS0}}$

Table 1.14 Pin Functions for the 128-Pin Package (3/3)

Signal Name	Pin Name	I/O	Power Supply	Description
UART0 to UART2, UART5 to UART7 I^2C mode	SDA0 to SDA2, SDA5	I/O	VCC1	Serial data I/O.
	SDA6, SDA7	I/O	VCC2	
	SCL0 to SCL2, SCL5	I/O	VCC1	Transmit/receive clock I/O.
	SCL6, SCL7	I/O	VCC2	
Serial interface SI/O3, SI/O4	CLK3, CLK4	I/O	VCC1	Transmit/receive clock I/O.
	SIN3, SIN4	I	VCC1	Serial data input.
	SOUT3, SOUT4	O	VCC1	Serial data output.
Multi-master I^2C-bus interface	SDAMM	I/O	VCC1	Serial data I/O (N-channel open drain output).
	SCLMM	I/O	VCC1	Transmit/receive clock I/O (N-channel open drain output).
CEC I/O	CEC	I/O	VCC1	CEC I/O (N-channel open drain output).
Reference voltage input	VREF	I	VCC1	Reference voltage input for the A/D and D/A converters.
A/D converter	AN0 to AN7	I	VCC1	Analog input.
	AN0_0 to AN0_7 AN2_0 to AN2_7	I	VCC2	
	$\overline{\text{ADTRG}}$	I	VCC1	External trigger input.
	ANEX0, ANEX1	I	VCC1	Extended analog input.
D/A converter	DA0, DA1	O	VCC1	Output pin the D/A converter.
I/O ports	P0_0 to P0_7 P1_0 to P1_7 P2_0 to P2_7 P3_0 to P3_7 P4_0 to P4_7 P5_0 to P5_7 P12_0 to P12_7 P13_0 to P13_7	I/O	VCC2	8-bit CMOS I/O ports. A direction register determines whether each pin is used as an input port or an output port. A pull-up resistor may be enabled or disabled for input ports in 4-bit units.
	P6_0 to P6_7 P7_0 to P7_7 P8_0 to P8_7 P9_0 to P9_7 P10_0 to P10_7 P11_0 to P11_7	I/O	VCC1	8-bit I/O ports having equivalent functions to P0. However, P7_0, P7_1, and P8_5 are N-channel open drain output ports. No pull-up resistor is provided. P8_5 is an input port for verifying the $\overline{\text{NMI}}$ pin level and shares a pin with $\overline{\text{NMI}}$.
	P14_0, P14_1	I/O	VCC1	I/O ports having equivalent functions to P0.

Table 1.15 Pin Functions for the 100-Pin Package (1/3)

Signal Name	Pin Name	I/O	Power Supply	Description
Power supply input	VCC1, VCC2, VSS	I	-	Apply 2.7 to 5.5 V to pins VCC1 and VCC2 (VCC1 ≥ VCC2) and 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	I	VCC1	This is the power supply for the A/D and D/A converters. Connect the AVCC pin to VCC1, and connect the AVSS pin to VSS.
Reset input	$\overline{\text{RESET}}$	I	VCC1	Driving this pin low resets the MCU.
CNVSS	CNVSS	I	VCC1	Input pin to switch processor modes. After a reset, to start operating in single-chip mode, connect the CNVSS pin to VSS via a resistor. To start operating in microprocessor mode, connect the pin to VCC1.
External data bus width select input	BYTE	I	VCC1	Input pin to select the data bus of the external area. The data bus is 16 bits when it is low, and 8 bits when it is high. This pin must be fixed either high or low. Connect the BYTE pin to VSS in single-chip mode.
Bus control pins	D0 to D7	I/O	VCC2	Inputs or outputs data (D0 to D7) while accessing an external area with a separate bus.
	D8 to D15	I/O	VCC2	Inputs or outputs data (D8 to D15) while accessing an external area with a 16-bit separate bus.
	A0 to A19	O	VCC2	Outputs address bits A0 to A19.
	A0/D0 to A7/D7	I/O	VCC2	Inputs or outputs data (D0 to D7) and outputs address bits (A0 to A7) by timesharing, while accessing an external area with an 8-bit multiplexed bus.
	A1/D0 to A8/D7	I/O	VCC2	Inputs or outputs data (D0 to D7) and outputs address bits (A1 to A8) by timesharing, while accessing an external area with a 16-bit multiplexed bus.
	$\overline{\text{CS0}}$ to $\overline{\text{CS3}}$	O	VCC2	Outputs chip-select signals $\overline{\text{CS0}}$ to $\overline{\text{CS3}}$ to specify an external area.
	$\overline{\text{WRL}}$/$\overline{\text{WR}}$ $\overline{\text{WRH}}$/$\overline{\text{BHE}}$ $\overline{\text{RD}}$	O	VCC2	Outputs $\overline{\text{WRL}}$, $\overline{\text{WRH}}$, ($\overline{\text{WR}}$, $\overline{\text{BHE}}$), and $\overline{\text{RD}}$ signals. $\overline{\text{WRL}}$ and $\overline{\text{WRH}}$ can be switched with $\overline{\text{BHE}}$ and $\overline{\text{WR}}$. • $\overline{\text{WRL}}$, $\overline{\text{WRH}}$, and $\overline{\text{RD}}$ selected If the external data bus is 16 bits, data is written to an even address in an external area when $\overline{\text{WRL}}$ is driven low. Data is written to an odd address when $\overline{\text{WRH}}$ is driven low. Data is read when $\overline{\text{RD}}$ is driven low. • $\overline{\text{WR}}$, $\overline{\text{BHE}}$, and $\overline{\text{RD}}$ selected Data is written to an external area when $\overline{\text{WR}}$ is driven low. Data in an external area is read when $\overline{\text{RD}}$ is driven low. An odd address is accessed when $\overline{\text{BHE}}$ is driven low. Select $\overline{\text{WR}}$, $\overline{\text{BHE}}$, and $\overline{\text{RD}}$ when using an 8-bit external data bus.
	ALE	O	VCC2	Outputs an ALE signal to latch the address.
	$\overline{\text{HOLD}}$	I	VCC2	$\overline{\text{HOLD}}$ input is unavailable. Connect the $\overline{\text{HOLD}}$ pin to VCC2 via a resistor (pull-up).
	$\overline{\text{HLDA}}$	O	VCC2	In a hold state, $\overline{\text{HLDA}}$ outputs a low-level signal.
	$\overline{\text{RDY}}$	I	VCC2	The MCU bus is placed in a wait state while the $\overline{\text{RDY}}$ pin is driven low.

Power supply: VCC2 is used to supply power to the external bus associated pins. The dual power supply configuration allows VCC2 to interface at a different voltage than VCC1.

3.2 Memory Map

Special function registers (SFRs) are allocated from address 00000h to 003FFh and from 0D000h to 0D7FFh. Peripheral function control registers are located here. All blank areas within SFRs are reserved. Do not access these areas.

Internal RAM is allocated from address 00400h and higher, with 10 KB of internal RAM allocated from 00400h to 02BFFh. Internal RAM is used not only for data storage, but also for the stack area when subroutines are called or when an interrupt request is accepted.

The internal ROM is flash memory. Three internal ROM areas are available: data flash, program ROM 1, and program ROM 2.

The data flash is allocated from 0E000h to 0FFFFh. This data flash area is mostly used for data storage, but can also store programs.

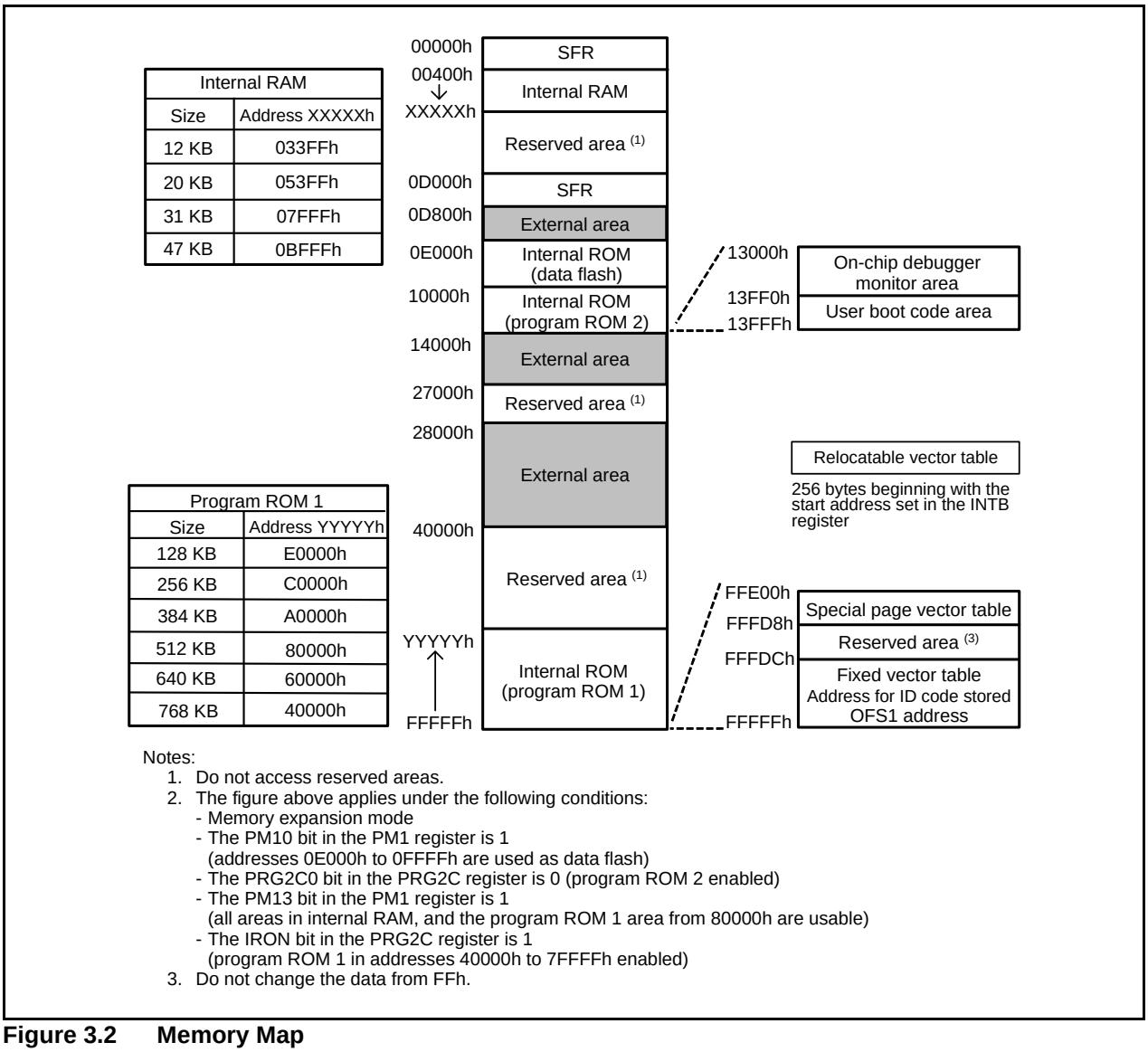
Program ROM 2 is allocated from 10000h to 13FFFh. Program ROM 1 is allocated from FFFFFh and lower, with the 64 KB program ROM 1 area allocated from address F0000h to FFFFFh.

The special page vectors are allocated from FFE00h to FFFD7h. They are used for the JMPS and JSRS instructions. Refer to the M16C/60, M16C/20, M16C/Tiny Series Software Manual for details.

The fixed vector table for interrupts is allocated from FFFDCh to FFFFFh.

The 256 bytes beginning with the start address set in the INTB register compose the relocatable vector table for interrupts.

Figure 3.2 shows the Memory Map.



Notes:
1. Do not access reserved areas.
2. The figure above applies under the following conditions:
   - Memory expansion mode
   - The PM10 bit in the PM1 register is 1
     (addresses 0E000h to 0FFFFh are used as data flash)
   - The PRG2C0 bit in the PRG2C register is 0 (program ROM 2 enabled)
   - The PM13 bit in the PM1 register is 1
     (all areas in internal RAM, and the program ROM 1 area from 80000h are usable)
   - The IRON bit in the PRG2C register is 1
     (program ROM 1 in addresses 40000h to 7FFFFh enabled)
3. Do not change the data from FFh.

Figure 3.2 Memory Map

Table 4.2 SFR Information (2) (1)

Address	Register	Symbol	Reset Value
0020h			
0021h			
0022h	40 MHz On-Chip Oscillator Control Register 0	FRA0	XXXX XX00b
0023h			
0024h			
0025h			
0026h	Voltage Monitor Function Select Register	VWCE	00h
0027h			
0028h	Voltage Detector 1 Level Select Register	VD1LS	0000 1010b(2)
0029h			
002Ah	Voltage Monitor 0 Control Register	VW0C	1000 XX10b (2)
002Bh	Voltage Monitor 1 Control Register	VW1C	1000 1010b (2)
002Ch	Voltage Monitor 2 Control Register	VW2C	1000 0X10b (2)
002Dh			
002Eh			
002Fh			
0030h			
0031h			
0032h			
0033h			
0034h			
0035h			
0036h			
0037h			
0038h			
0039h			
003Ah			
003Bh			
003Ch			
003Dh			
003Eh			
003Fh			

X: Undefined

Notes:
1. The blank areas are reserved. No access is allowed.
2. This is the reset value after hardware reset. Refer to the explanation of each register for details.

Table 4.9 SFR Information (9) (1)

Address	Register	Symbol	Reset Value
0240h			
0241h			
0242h			
0243h			
0244h	UART0 Special Mode Register 4	U0SMR4	00h
0245h	UART0 Special Mode Register 3	U0SMR3	000X 0X0Xb
0246h	UART0 Special Mode Register 2	U0SMR2	X000 0000b
0247h	UART0 Special Mode Register	U0SMR	X000 0000b
0248h	UART0 Transmit/Receive Mode Register	U0MR	00h
0249h	UART0 Bit Rate Register	U0BRG	XXh
024Ah	UART0 Transmit Buffer Register	U0TB	XXh
024Bh			XXh
024Ch	UART0 Transmit/Receive Control Register 0	U0C0	0000 1000b
024Dh	UART0 Transmit/Receive Control Register 1	U0C1	00XX 0010b
024Eh	UART0 Receive Buffer Register	U0RB	XXh
024Fh			XXh
0250h	UART Transmit/Receive Control Register 2	UCON	X000 0000b
0251h			
0252h	UART Clock Select Register	UCLKSEL0	X0h
0253h			
0254h	UART1 Special Mode Register 4	U1SMR4	00h
0255h	UART1 Special Mode Register 3	U1SMR3	000X 0X0Xb
0256h	UART1 Special Mode Register 2	U1SMR2	X000 0000b
0257h	UART1 Special Mode Register	U1SMR	X000 0000b
0258h	UART1 Transmit/Receive Mode Register	U1MR	00h
0259h	UART1 Bit Rate Register	U1BRG	XXh
025Ah	UART1 Transmit Buffer Register	U1TB	XXh
025Bh			XXh
025Ch	UART1 Transmit/Receive Control Register 0	U1C0	0000 1000b
025Dh	UART1 Transmit/Receive Control Register 1	U1C1	00XX 0010b
025Eh	UART1 Receive Buffer Register	U1RB	XXh
025Fh			XXh
0260h			
0261h			
0262h			
0263h			
0264h	UART2 Special Mode Register 4	U2SMR4	00h
0265h	UART2 Special Mode Register 3	U2SMR3	000X 0X0Xb
0266h	UART2 Special Mode Register 2	U2SMR2	X000 0000b
0267h	UART2 Special Mode Register	U2SMR	X000 0000b
0268h	UART2 Transmit/Receive Mode Register	U2MR	00h
0269h	UART2 Bit Rate Register	U2BRG	XXh
026Ah	UART2 Transmit Buffer Register	U2TB	XXh
026Bh			XXh
026Ch	UART2 Transmit/Receive Control Register 0	U2C0	0000 1000b
026Dh	UART2 Transmit/Receive Control Register 1	U2C1	0000 0010b
026Eh	UART2 Receive Buffer Register	U2RB	XXh
026Fh			XXh

X: Undefined

Note:
1. The blank areas are reserved. No access is allowed.

4.2 Notes on SFRs

4.2.1 Register Settings

Table 4.19 lists Registers with Write-Only Bits and registers whose function differs between reading and writing. Set these registers with immediate values. Do not use read-modify-write instructions. When establishing the next value by altering the existing value, write the existing value to the RAM as well as to the register. Transfer the next value to the register after making changes in the RAM.
Read-modify-write instructions can be used when writing to the no register bits.

Table 4.19 Registers with Write-Only Bits

Address	Register	Symbol
0249h	UART0 Bit Rate Register	U0BRG
024Bh to 024Ah	UART0 Transmit Buffer Register	U0TB
0259h	UART1 Bit Rate Register	U1BRG
025Bh to 025Ah	UART1 Transmit Buffer Register	U1TB
0269h	UART2 Bit Rate Register	U2BRG
026Bh to 026Ah	UART2 Transmit Buffer Register	U2TB
0273h	SI/O3 Bit Rate Register	S3BRG
0277h	SI/O4 Bit Rate Register	S4BRG
0289h	UART5 Bit Rate Register	U5BRG
028Bh to 028Ah	UART5 Transmit Buffer Register	U5TB
0299h	UART6 Bit Rate Register	U6BRG
029Bh to 029Ah	UART6 Transmit Buffer Register	U6TB
02A9h	UART7 Bit Rate Register	U7BRG
02ABh to 02AAh	UART7 Transmit Buffer Register	U7TB
02B6h	I2C0 Control Register 1	S3D0
02B8h	I2C0 Status Register 0	S10
0303h to 0302h	Timer A1-1 Register	TA11
0305h to 0304h	Timer A2-1 Register	TA21
0307h to 0306h	Timer A4-1 Register	TA41
030Ah	Three-Phase Output Buffer Register 0	IDB0
030Bh	Three-Phase Output Buffer Register 1	IDB1
030Ch	Dead Time Timer	DTT
030Dh	Timer B2 Interrupt Generation Frequency Set Counter	ICTB2
0327h to 0326h	Timer A0 Register	TA0
0329h to 0328h	Timer A1 Register	TA1
032Bh to 032Ah	Timer A2 Register	TA2
032Dh to 032Ch	Timer A3 Register	TA3
032Fh to 032Eh	Timer A4 Register	TA4
037Dh	Watchdog Timer Refresh Register	WDTR
037Eh	Watchdog Timer Start Register	WDTS

Table 5.3 Recommended Operating Conditions (2/3)

V_{CC1} = V_{CC2} = 2.7 to 5.5 V at T_{opr} = -20°C to 85°C/-40°C to 85°C unless otherwise specified.

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
$I_{OL(sum)}$	Low peak output current	Sum of $I_{OL(peak)}$ at P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0 to P14_1			80.0	mA
		Sum of $I_{OL(peak)}$ at P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_5, P12_0 to P12_7, P13_0 to P13_7			80.0	mA
$I_{OL(peak)}$	Low peak output current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1			10.0	mA
$I_{OL(avg)}$	Low average output current (1)	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1			5.0	mA
$f_{(XIN)}$	Main clock input oscillation frequency	V_{CC1} = 2.7 V to 5.5 V	2		20	MHz
$f_{(XCIN)}$	Sub clock oscillation frequency			32.768	50	kHz
$f_{(PLL)}$	PLL clock oscillation frequency	V_{CC1} = 2.7 V to 5.5 V	10		32	MHz
$f_{(BCLK)}$	CPU operation clock		2		32	MHz
$t_{SU(PLL)}$	PLL frequency synthesizer stabilization wait time	V_{CC1} = 5.0 V			2	ms
		V_{CC1} = 3.0 V			3	ms

Note:
1. The average output current is the mean value within 100 ms.

$V_{CC1} = V_{CC2} = 5\ V$

Timing Requirements

($V_{CC1} = V_{CC2} = 5$ V, $V_{SS} = 0$ V, at T_{opr} = -20°C to 85°C/-40°C to 85°C unless otherwise specified)

5.2.2.3 Timer A Input

Table 5.26 Timer A Input (Counter Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	100		ns
$t_{w(TAH)}$	TAiIN input high pulse width	40		ns
$t_{w(TAL)}$	TAiIN input low pulse width	40		ns

Table 5.27 Timer A Input (Gating Input in Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	400		ns
$t_{w(TAH)}$	TAiIN input high pulse width	200		ns
$t_{w(TAL)}$	TAiIN input low pulse width	200		ns

Table 5.28 Timer A Input (External Trigger Input in One-Shot Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	200		ns
$t_{w(TAH)}$	TAiIN input high pulse width	100		ns
$t_{w(TAL)}$	TAiIN input low pulse width	100		ns

Table 5.29 Timer A Input (External Trigger Input in Pulse Width Modulation Mode and Programmable Output Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(TAH)}$	TAiIN input high pulse width	100		ns
$t_{w(TAL)}$	TAiIN input low pulse width	100		ns

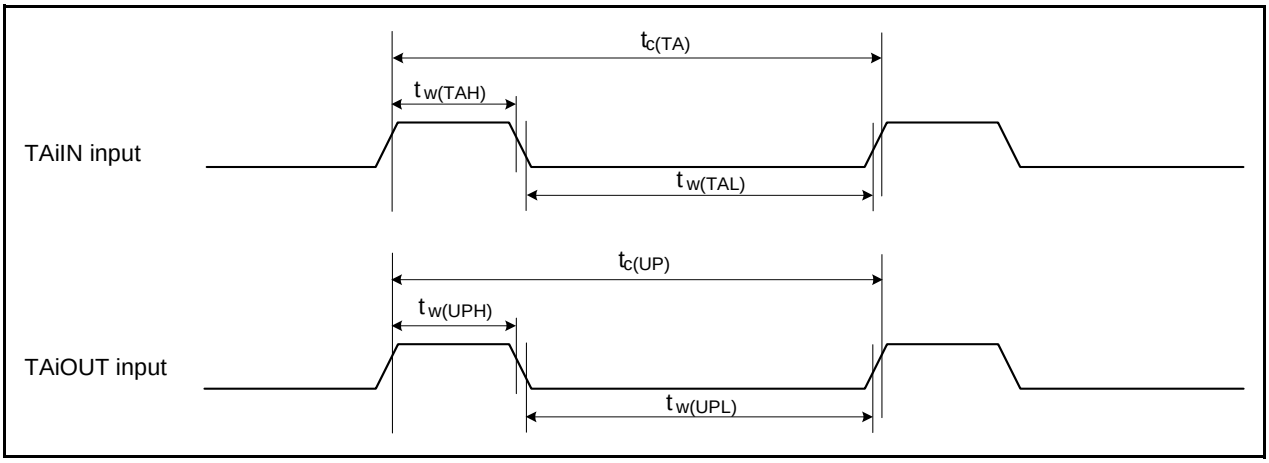
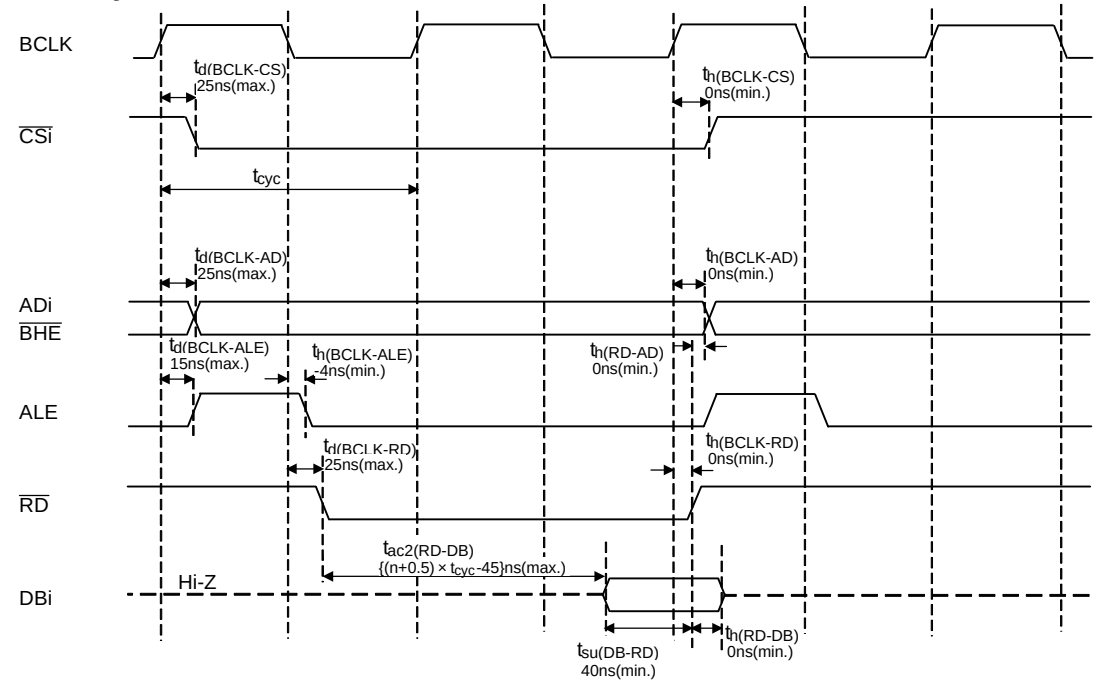


Figure 5.7 Timer A Input

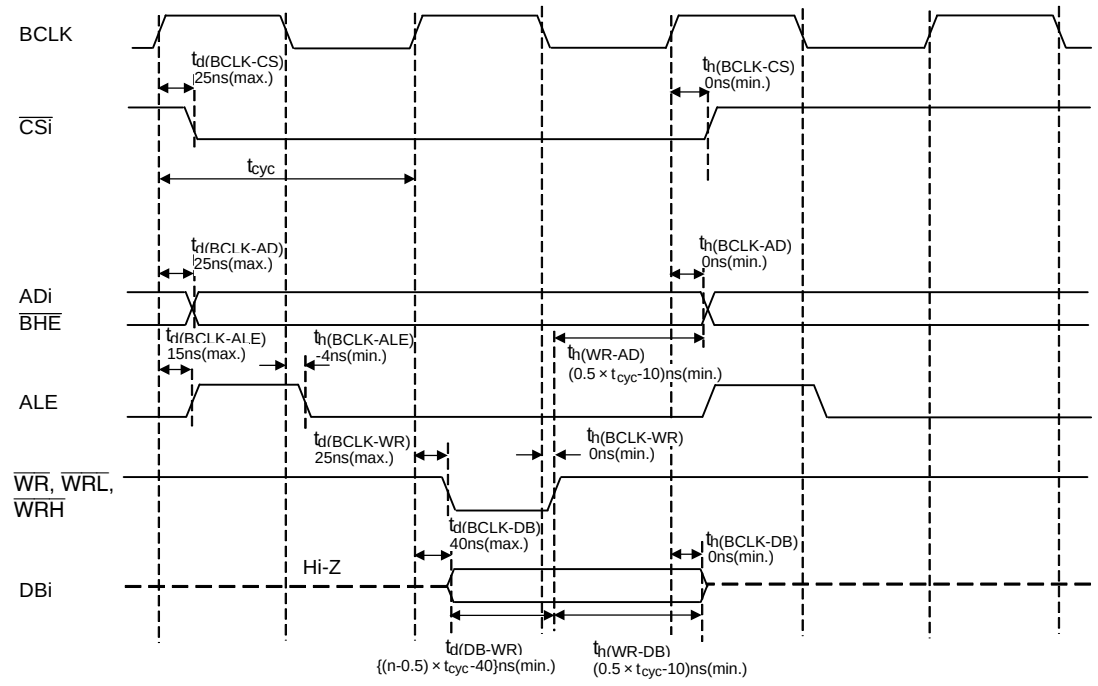
Memory Expansion Mode and Microprocessor Mode
(in 1 to 3 waits setting and when accessing external area)

$V_{CC1} = V_{CC2} = 5V$

Read timing



Write timing



$$t_{cyc} = \frac{1}{f_{(BCLK)}}$$

Measuring conditions

- $V_{CC1} = V_{CC2} = 5V$
- Input timing voltage: $V_{IL} = 0.8$ V, $V_{IH} = 2.0$ V
- Output timing voltage: $V_{OL} = 0.4$ V, $V_{OH} = 2.4$ V

n: 1 (when 1 wait)
2 (when 2 waits)
3 (when 3 waits)

Figure 5.16 Timing Diagram

5.3 Electrical Characteristics (V_{CC1} = V_{CC2} = 3 V)

5.3.1 Electrical Characteristics

VCC1 = VCC2 = 3 V

Table 5.43 Electrical Characteristics (1) [1]

V_{CC1} = V_{CC2} = 2.7 to 3.3 V, V_{SS} = 0 V at T_{opr} = -20°C to 85°C/-40°C to 85°C, $f_{(BCLK)}$ = 32 MHz unless otherwise specified.

Symbol	Parameter			Measuring Condition	Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	High output voltage	P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1		I_{OH} = –1 mA	V_{CC1} – 0.5		V_{CC1}	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7		I_{OH} = –1 mA	V_{CC2} – 0.5		V_{CC2}	
V_{OH}	High output voltage XOUT		HIGH POWER	I_{OH} = –0.1 mA	V_{CC1} – 0.5		V_{CC1}	V
			LOW POWER	I_{OH} = –50 µA	V_{CC1} – 0.5		V_{CC1}	
	High output voltage XCOUT		HIGH POWER	With no load applied		2.6		V
			LOW POWER	With no load applied		2.2		
V_{OL}	Low output voltage	P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1		I_{OL} = 1 mA			0.5	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7		I_{OL} = 1 mA			0.5	
		CEC		I_{OL} = 1 mA		0	0.5	V
V_{OL}	Low output voltage XOUT		HIGH POWER	I_{OL} = 0.1 mA			0.5	V
			LOW POWER	I_{OL} = 50 µA			0.5	
	Low output voltage XCOUT		HIGH POWER	With no load applied		0		V
			LOW POWER	With no load applied		0		
V_{T+}-V_{T-}	Hysteresis	$\overline{HOLD}$, $\overline{RDY}$, TA0IN to TA4IN, TB0IN to TB5IN, $\overline{INT0}$ to $\overline{INT7}$, $\overline{NMI}$, $\overline{ADTRG}$, $\overline{CTS0}$ to $\overline{CTS2}$, $\overline{CTS5}$ to $\overline{CTS7}$, SCL0 to SCL2, SCL5 to SCL7, SDA0 to SDA2, SDA5 to SDA7, CLK0 to CLK7, TA0OUT to TA4OUT, $\overline{KI0}$ to $\overline{KI3}$, RXD0 to RXD2, RXD5 to RXD7, SIN3, SIN4, $\overline{SD}$, PMC0, PMC1, SCLMM, SDAMM, ZP, IDU, IDV, IDW			0.2		1.0	V
		CEC			0.2	0.5	1.0	V
		$\overline{RESET}$			0.2		1.8	V
I_{IH}	High input current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1 XIN, $\overline{RESET}$, CNVSS, BYTE		V_I = 3 V			4.0	µA
–	Leakage current in powered-off state		CEC	V_{CC1} = 0 V			1.8	µA
I_{IL}	Low input current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1 XIN, $\overline{RESET}$, CNVSS, BYTE		V_I = 0 V			–4.0	µA
R_{PULLUP}	Pull-up resistance	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1		V_I = 0 V	50	80	150	kΩ
R_{fXIN}	Feedback resistance XIN					3.0		MΩ
V_{RAM}	RAM retention voltage			In stop mode	1.8			V

Note:
1. When $V_{CC1} \neq V_{CC2}$, refer to 5 V or 3 V standard depending on the voltage.

$V_{CC1} = V_{CC2} = 3\ V$

5.3.2 Timing Requirements (Peripheral Functions and Others)

($V_{CC1} = V_{CC2} = 3$ V, $V_{SS} = 0$ V, at $T_{opr} = -20°C$ to 85°C/-40°C to 85°C unless otherwise specified)

5.3.2.1 Reset Input ($\overline{\text{RESET}}$ Input)

Table 5.47 Reset Input ($\overline{\text{RESET}}$ Input)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(RSTL)}$	$\overline{\text{RESET}}$ input low pulse width	10		µs

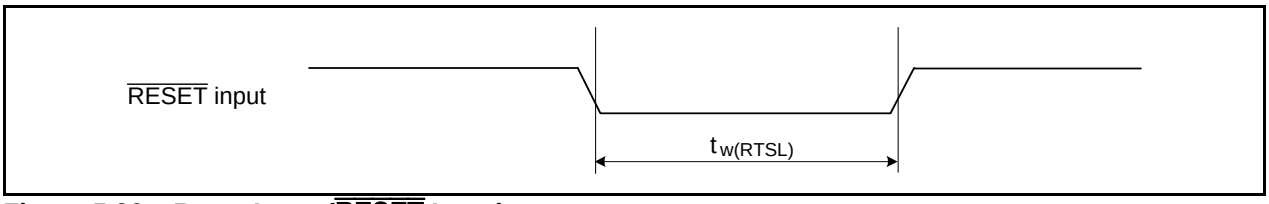


Figure 5.20 Reset Input ($\overline{\text{RESET}}$ Input)

5.3.2.2 External Clock Input

Table 5.48 External Clock Input (XIN Input) (1)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t_c	External clock input cycle time	50		ns
$t_{w(H)}$	External clock input high pulse width	20		ns
$t_{w(L)}$	External clock input low pulse width	20		ns
t_r	External clock rise time		9	ns
t_f	External clock fall time		9	ns

Note:
1. The condition is $V_{CC1} = V_{CC2} = 2.7$ to 3.0 V.

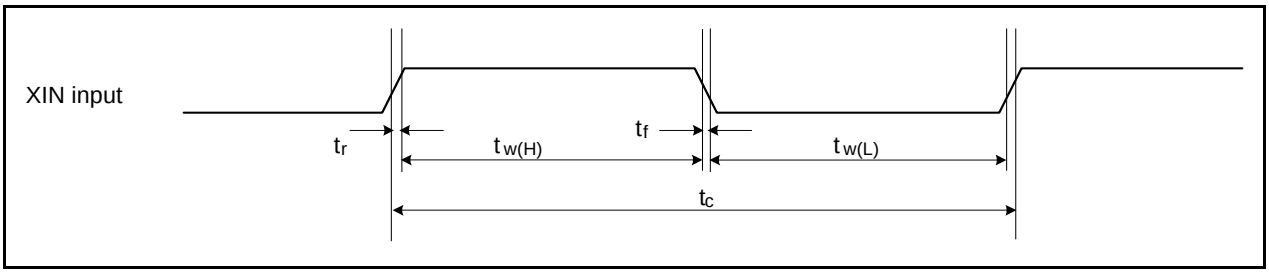
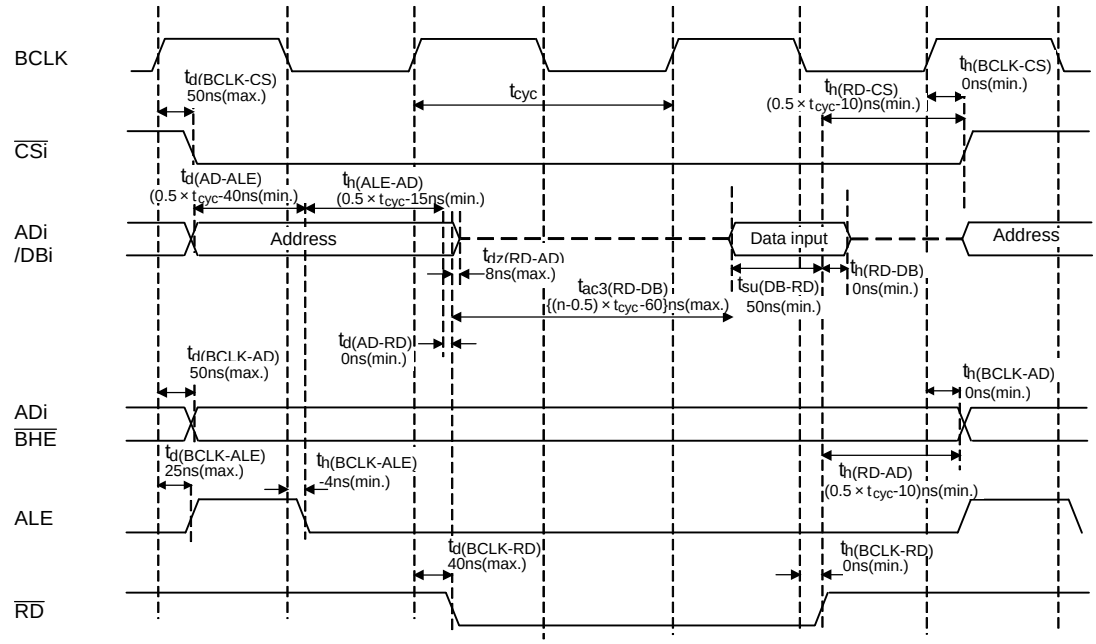


Figure 5.21 External Clock Input (XIN Input)

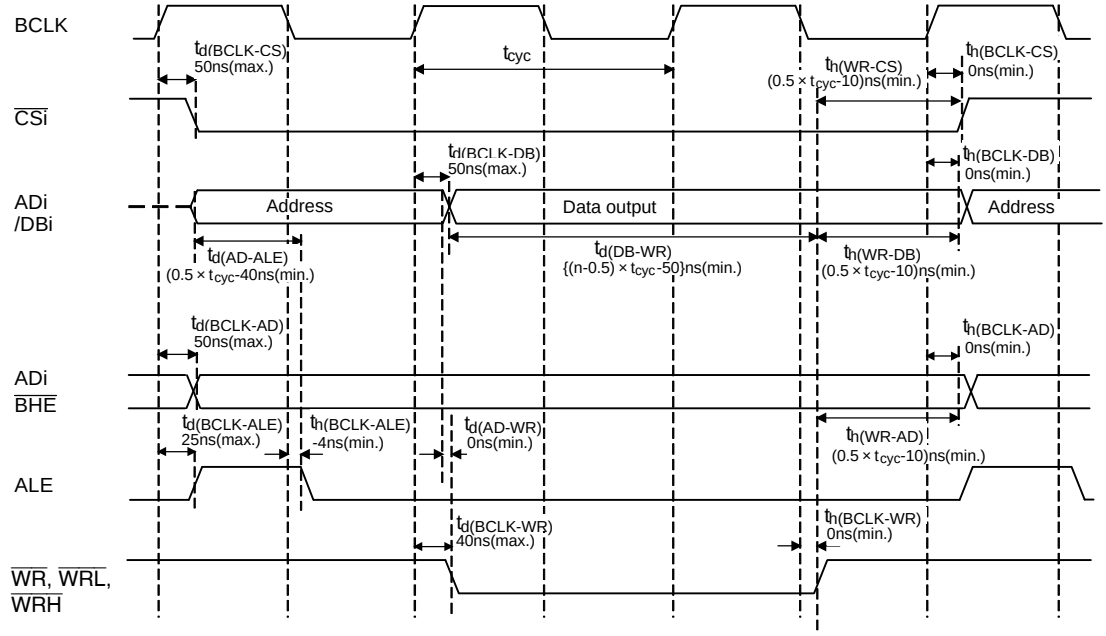
$V_{CC1} = V_{CC2} = 3V$

Memory Expansion Mode and Microprocessor Mode
(in 2 or 3 waits setting, and when accessing external area and using multiplexed bus)

Read timing



Write timing



$$t_{cyc} = \frac{1}{f_{(BCLK)}}$$

Measuring conditions

- $V_{CC1} = V_{CC2} = 3V$
- Input timing voltage: $V_{IL} = 0.6$ V, $V_{IH} = 2.4$ V
- Output timing voltage: $V_{OL} = 1.5$ V, $V_{OH} = 1.5$ V

n: 2 (when 2 waits)
3 (when 3 waits)

Figure 5.32 Timing Diagram

$V_{CC1} = V_{CC2} = 3\ V$

Switching Characteristics

($V_{CC1} = V_{CC2} = 3$ V, $V_{SS} = 0$ V, at $T_{opr} = -20°C$ to 85°C/-40°C to 85°C unless otherwise specified)

5.3.4.4 In Wait State Setting 2φ + 3φ, 2φ + 4φ, 3φ + 4φ, and 4φ + 5φ, and When Accessing External Area

Table 5.64 Memory Expansion and Microprocessor Modes (in Wait State Setting 2φ + 3φ, 2φ + 4φ, 3φ + 4φ, and 4φ + 5φ, and When Accessing External Area)

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	See Figure 5.29		30	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		0		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		0		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(Note 2)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			30	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		0		ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time			25	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time		-4		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			30	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			30	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{h(BCLK-DB)}$	Data output hold time (in relation to BCLK) (3)		0		ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(Note 1)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR) (3)		(Note 2)		ns

Notes:

1. Calculated according to the BCLK frequency as follows:

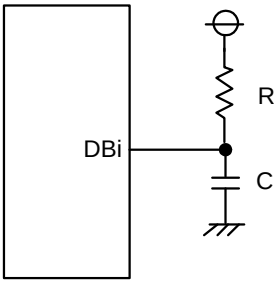
$$\frac{(n-0.5)\times 10^9}{f_{(BCLK)}} - 40[ns]$$

n is 3 for 2φ + 3φ, 4 for 2φ + 4φ, 4 for 3φ + 4φ, and 5 for 4φ + 5φ.

2. Calculated according to the BCLK frequency as follows:

$$\frac{0.5\times 10^9}{f_{(BCLK)}} - 10[ns]$$

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.
Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.
Hold time of data bus is expressed in
$t = -CR \times \ln(1 - V_{OL}/V_{CC2})$
by a circuit of the right figure.
For example, when $V_{OL} = 0.2V_{CC2}$, C = 30 pF, R = 1 kΩ, hold time of output low level is
$t = -30\ pF \times 1\ k\Omega \times \ln(1 - 0.2V_{CC2}/V_{CC2})$
= 6.7 ns.



REVISION HISTORY	M16C/65 Group Datasheet

Rev.	Date	Description	
		Page	Summary
2.00	Dec 10, 2010	**Special Function Registers (SFRs)**	
		31	Table 4.1 SFR Information (1): • Deleted “the VCR1 register, the VCR2 register” from note 2. • Deleted notes 5 to 6 and added note 5.
		32	Table 4.2 SFR Information (2): Deleted notes 2 to 7 and added note 2.
		49	4.2.1 Register Settings: Added the description regarding read-modify-write instructions.
		50	Table 4.20 Read-Modify-Write Instructions: Added.
		Electrical Characteristics	
		51	Table 5.1 Absolute Maximum Ratings: Added a row for the data area value to T_{opr} (Flash program erase).
		52	Table 5.2 Recommended Operating Conditions (1/3): Added rows for the CEC value to V_{CC1}, V_{CC2}, V_{IH}, and V_{IL}.
		57	Table 5.9 Flash Memory (Program ROM 1, 2) Electrical Characteristics: Added a condition to the Read voltage row.
		60	Table 5.14 Power-On Reset Circuit: • Added the $t_{w(por)}$ row. • Added the last line in note 1.
		60	Figure 5.3 Power-On Reset Circuit Electrical Characteristics: Deleted note 2.
		64	Table 5.20 Electrical Characteristics (2): Added “ZP, IDU, IDV, IDW” to the V_{T+} - V_{T-} row.
		65	Table 5.21 Electrical Characteristics (3): Moved R5F3651ENFC and R5F3651EDFC to Table 5.22 Electrical Characteristics (4).
		73, 96	5.2.2.7 and 5.3.2.7 Multi-master I^2C-bus: Added.
		74 to 81, 97 to 104	Table 5.37 to Table 5.42 and Table 5.60 to Table 5.65 Memory Expansion Mode and Microprocessor Mode: Deleted the following: • $\overline{HOLD}$ input setup time • $\overline{HOLD}$ input hold time • $\overline{HLDA}$ output delay time
		74	Table 5.37 Memory Expansion Mode and Microprocessor Mode: Changed $\overline{RDY}$ input setup time from 30.
		75, 98	Figure 5.13 and Figure 5.28 Timing Diagram: Deleted lower figure (Common to wait state and no wait state settings).
		86, 109	Figure 5.19 and Figure 5.34 Timing Diagram: Changed the width of th(RD-AD).
		87	Table 5.43 Electrical Characteristics (1): • Added rows for the CEC value to V_{OL}, V_{T+}-V_{T-}, and Leakage current in powered-off state. • Added “ZP, IDU, IDV, IDW” to the V_{T+} - V_{T-} row.
		88	Table 5.44 Electrical Characteristics (2): Moved R5F3651ENFC and R5F3651EDFC to Table 5.45 Electrical Characteristics (3).
		88 to 90	Table 5.44 to Table 5.46 Electrical Characteristics (2) to (4): Changed “VCC1 = 5.0 V” to "VCC1 = 3.0 V" in the During flash memory program and During flash memory erase rows.
		97	Table 5.60 Memory Expansion Mode and Microprocessor Mode: Changed $\overline{RDY}$ input setup time from 40.
2.10	Ju. 31, 2012	**Electrical Characteristics**	
		Vcc = 5 V	
		65, 66, 67	Table 5.21 Electrical Characteristics (3), Table 5.22 Electrical Characteristics (4), and Table 5.23 Electrical Characteristics (5): Changed the Measuring Condition column of 40 MHz on-chip oscillator for the 40 MHz on-chip oscillator mode in the I_{CC}.
		Vcc = 3 V	
		88, 89, 90	Table 5.44 Electrical Characteristics (2), Table 5.45 Electrical Characteristics (3), and Table 5.46 Electrical Characteristics (4): Changed the Measuring Condition column of 40 MHz on-chip oscillator for the 40 MHz on-chip oscillator mode in the I_{CC}.

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

   — The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.